

**Abstract of the Disclosure**

A method of fabricating a semiconductor apparatus includes forming a base member and a conductive layer on a first surface of a semiconductor substrate. The conductive layer has an extended portion that extends onto the base member. A first surface of the semiconductor substrate is placed to face a connection substrate, the extended portion of the conductive layer is then connected to the connection substrate, and a seal member is supplied in a space between the semiconductor substrate and the connection substrate.